

S/N 10/623,788

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Leonard Forbes et al. Examiner: Pamela E. Perkins
Serial No.: 10/623,788 Group Art Unit: 2822
Filed: July 21, 2003 Docket: 1303.109US1
Title: STRAINED SEMICONDUCTOR BY FULL WAFER BONDING

COMMUNICATION CONCERNING RELATED APPLICATION(S)

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Applicants would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

<u>Serial/Patent No.</u>	<u>Filing Date/Issue Date</u>	<u>Attorney Docket</u>	<u>Title</u>
11/210927	August 24, 2005	1303.089US2	MICRO-MECHANICALLY STRAINED SEMICONDUCTOR FILM
11/167894	June 27, 2005	1303.108US3	GETTERING USING VOIDS FORMED BY SURFACE TRANSFORMATION
11/210373	August 24, 2005	1303.094US2	STRAINED Si/SiGe STRUCTURES BY ION IMPLANTATION
11/214495	August 29, 2005	1303.098US2	SEMICONDUCTOR ON INSULATOR STRUCTURE

Continuations and divisionals may be later filed on the cases listed above, or cited to the Examiner in any previous Communication Concerning Related Applications. Applicants request that the Examiner review all continuations and divisionals of the above-listed or previously-cited patent applications before allowing the claims of the present patent application.

Respectfully submitted,
LEONARD FORBES ET AL.

By Applicants' Representatives,
SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
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(612) 373-6960

Date 10-31-05 By M L R
Marvin L. Beekman
Reg. No. 38,377

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 31 day of October, 2005.

KACIA LEE
Name

Kacia Lee
Signature

S/N 10/623,788



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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Leonard Forbes et al.	Examiner:	Pamela E. Perkins
Serial No.:	10/623,788	Group Art Unit:	2822
Filed:	July 21, 2003	Docket:	1303.109US1
Title:	STRAINED SEMICONDUCTOR BY FULL WAFER BONDING		

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Supplemental Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(b), it is believed that no fee or statement is required with the Supplemental Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge the required fees to Deposit Account No. 19-0743 in order to have this Supplemental Information Disclosure Statement considered.

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Pursuant to 37 C.F.R. 1.98(a)(2), Applicant believes that copies of cited U.S. Patents and Published Applications are no longer required to be provided to the Office. Notification of this change was provided in the United States Patent and Trademark Office OG Notices dated October 12, 2004. Thus, Applicant has not included copies of any US Patents or Published Applications cited with this submission. Should the Office require copies to be provided, Applicant respectfully requests that notice of such requirement be directed to Applicant's below-signed representative. Applicant acknowledges the requirement to submit copies of foreign patent documents and non-patent literature in accordance with 37 C.F.R. 1.98(a)(2).


Respectfully submitted,

LEONARD FORBES ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
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Date 10-31-05

By 
Marvin L. Beekman
Reg. No. 38,377

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Name KACIA LEE

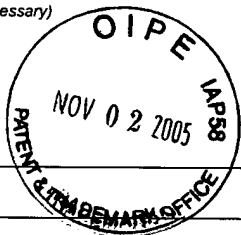

Signature

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number.

Substitute for form 1449A/PTO

**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

(Use as many sheets as necessary)



Complete if Known

Application Number	10/623,788
Filing Date	July 21, 2003
First Named Inventor	Forbes, Leonard
Group Art Unit	2822
Examiner Name	Perkins, Pamela

Sheet 1 of 1

Attorney Docket No: 1303.109US1

US PATENT DOCUMENTS

Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Filing Date If Appropriate
	US-2005/0087842-A1	04/28/2005	Forbes, L.	11/02/2004
	US-5,858,819	01/12/1999	Miyasaka, M.	02/15/1996
	US-6,107,661	08/22/2000	Okabe, Naoto , et al.	09/27/1996
	US-6,717,216	04/06/2004	Doris, B. B., et al.	12/12/2002
	US-6,825,102	11/30/2004	Bedell, S. W., et al.	09/18/2003

FOREIGN PATENT DOCUMENTS

Examiner Initials *	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	T ²
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OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS

Examiner Initials *	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
		KAL, S. , et al., "Strained Silicon-SiGe Devices Using Germanium Implantation", <u>IETE Journal of Research</u> , 43 (2-3), (Mar. 1997),185-192	
		XIAO, Q. , et al., "Preparation of thin Strained Si Film by Low Temperature Ge Ion Implantation and High Temperature Annealing", <u>Solid-State and Integrated Circuits Technology</u> , 2004. Proceedings 7th Int'l Conf., 3(3), (Oct. 18, 2004),2163-2166	

EXAMINER**DATE CONSIDERED**

Substitute Disclosure Statement Form (PTO-1449)

* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 809. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.
¹ Applicant's unique citation designation number (optional) ² Applicant is to place a check mark here if English language Translation is attached